

/ Descriptions

Silicon PNP transistor in a TO-3P Plastic Package.

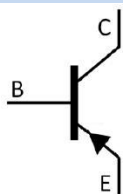
/ Features

Recommend for 100W high fidelity audio frequency amplifier output stage, Complementary to 2SC5200.

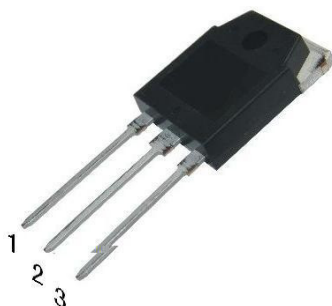
/ Applications

Power amplifier applications

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Collector PIN 3 Emitter

/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	R	O
h_{FE} Range	55~110	80~160

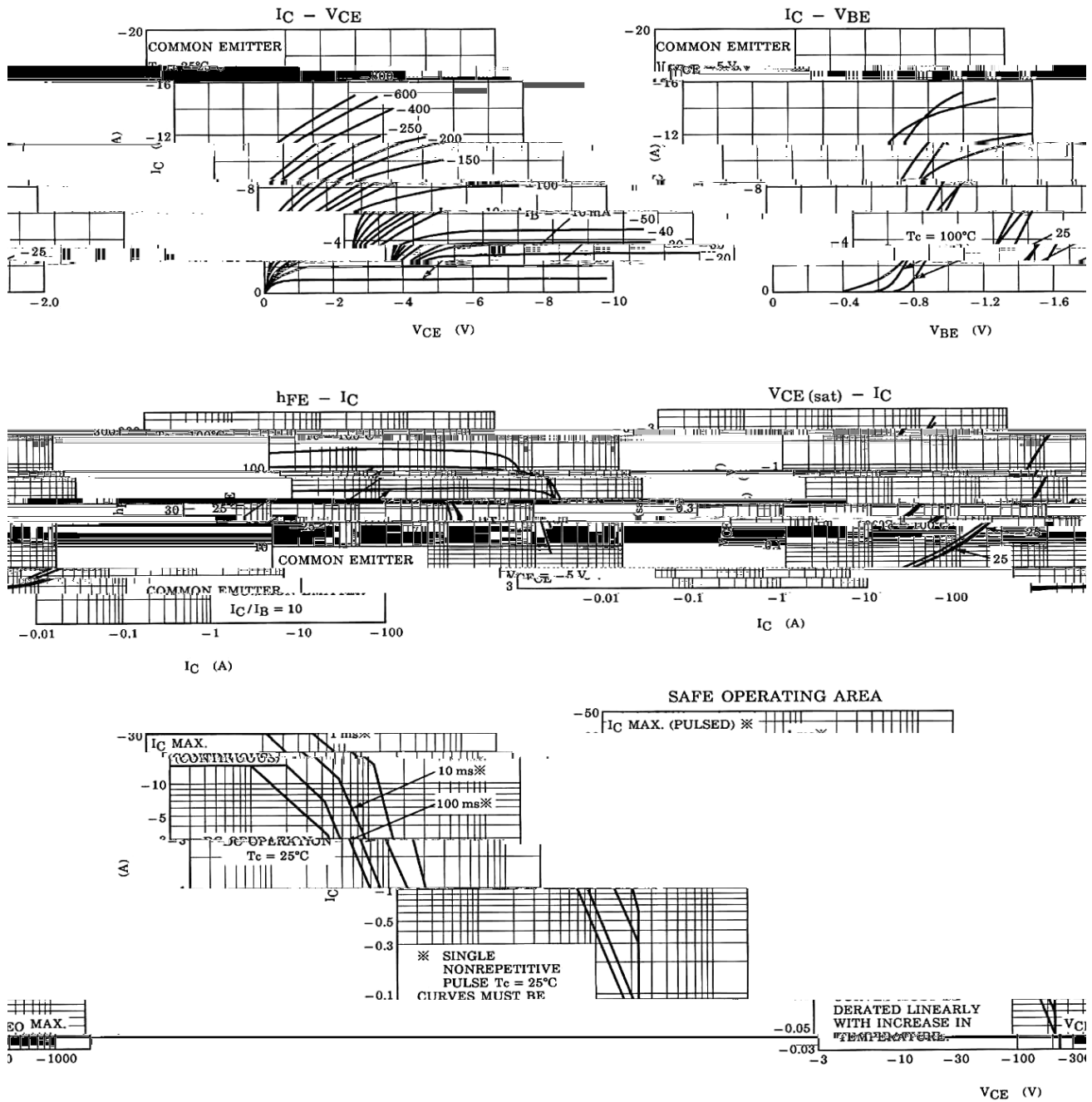
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-230	V
Collector to Emitter Voltage	V_{CEO}	-230	V
Emitter to Base Voltage	V_{EBO}	-5	V
Collector Current - Continuous	I_C	-15	A
Collector Current – Continuous(Pulse)	I_{CP}	-30	A
Base Current	I_B	-1.5	A
Collector Power Dissipation	$P_{C(TC=25)}$	150	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

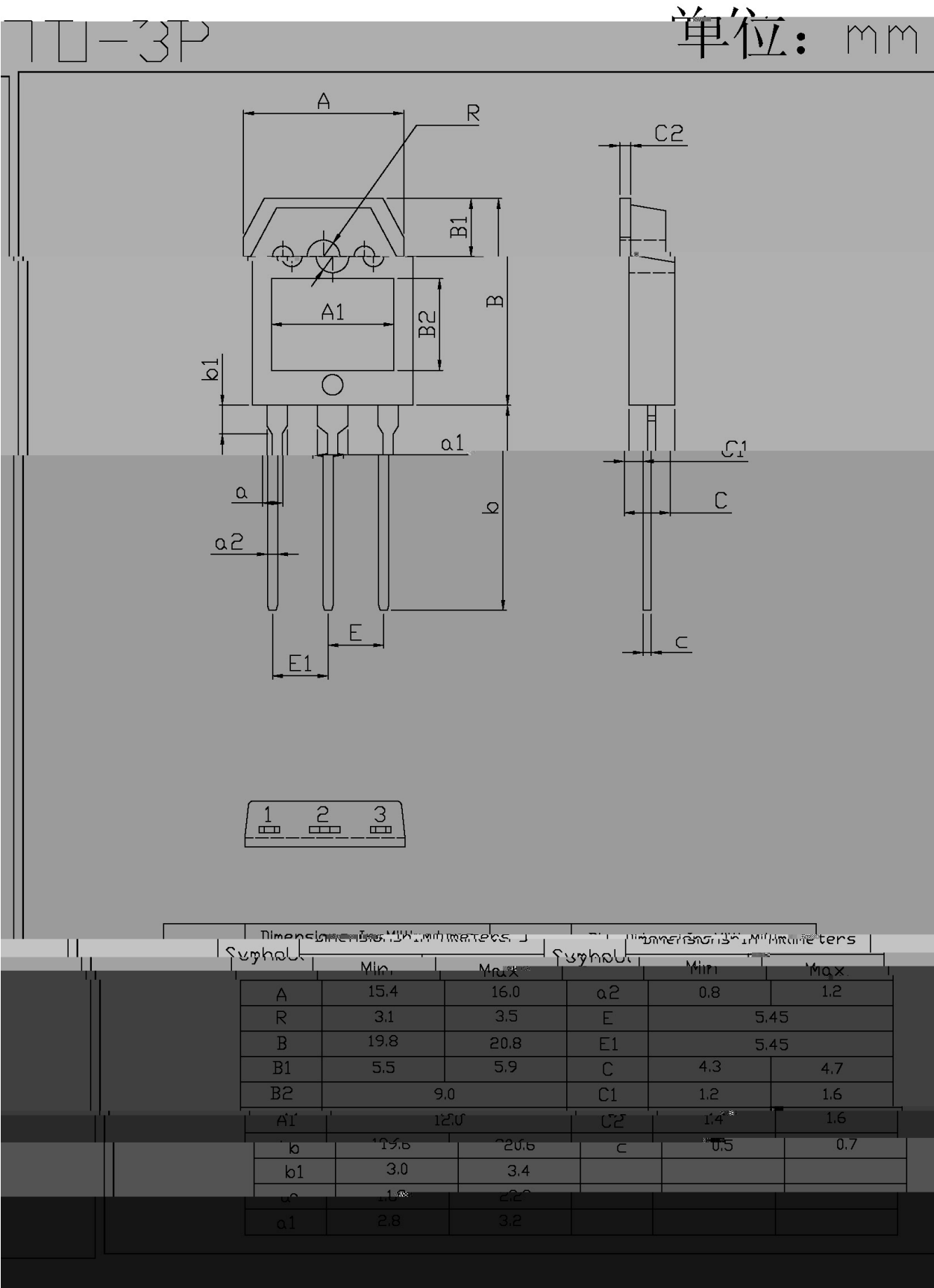
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=-50mA$ $I_B=0$	-230			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-230V$ $I_E=0$			-5	A
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=-5.0V$ $I_C=0$			-5	A
DC Current Gain	$h_{FE(1)}$	$V_{CE}=-5.0V$ $I_C=-1.0A$	55		160	
	$h_{FE(2)}$	$V_{CE}=-5.0V$ $I_C=-7.0A$	35	60		
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-8.0A$ $I_B=-0.8A$		-1.5	-3	V
Base to Emitter Voltage	V_{BE}	$V_{CE}=-5.0V$ $I_C=-7.0A$		-1	-1.5	V
Transition Frequency	f_T	$V_{CE}=-5.0V$ $I_C=-1.0A$		30		MHz
Collector Output Capacitance	C_{ob}	$V_{CB}=-10V$ $I_E=0$ $f=1.0MHz$		360		pF

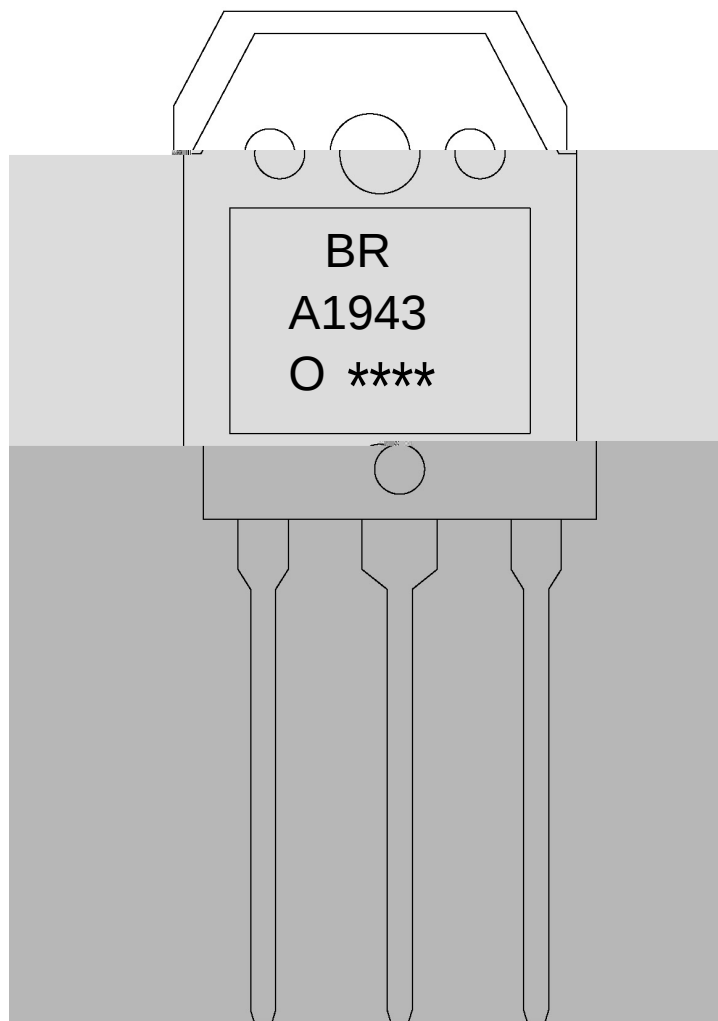
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



h_{FE}

Note:

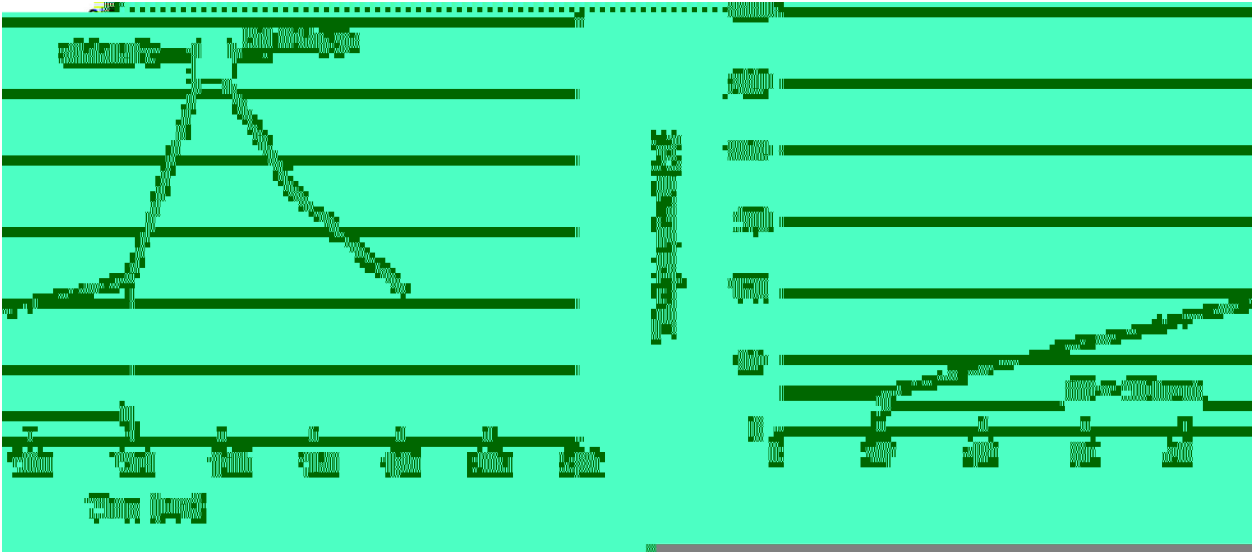
BR: Company Code.

A1943: Product Type.

O: h_{FE} Classifications Symbol.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



- 1 25 150 60 90sec;

2 255 5 5 0.5sec;

3 2 10 /sec.
- Note:

1.Preheating:25~150 , Time:60~90sec.

2.Peak Temp.:255 5 , Duration:5 0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ TUBE

Package Type 封装形式	Units 包装数量		Dimension 包装尺寸 (unit: mm ³)
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	